# MOSFET - SiC Power, Single N-Channel 1200 V, 160 mΩ, 17 A

### **NVHL160N120SC1**

#### **Features**

- Typ.  $R_{DS(on)} = 160 \text{ m}\Omega$
- Ultra Low Gate Charge (typ.  $Q_{G(tot)} = 34 \text{ nC}$ )
- Low Effective Output Capacitance (typ. C<sub>oss</sub> = 50 pF)
- 100% UIL Tested
- Qualified According to AEC-Q101
- These Devices are RoHS Compliant

#### **Typical Applications**

- Automotive On Board Charger
- Automotive DC/DC Converter for EV/HEV

#### MAXIMUM RATINGS (T<sub>J</sub> = 25°C unless otherwise noted)

Parame	Symbol	Value	Unit		
Drain-to-Source Voltage			V <sub>DSS</sub>	1200	V
Gate-to-Source Voltage			V <sub>GS</sub>	-15/+25	V
Recommended Operation Values of Gate-to-Source Voltage	T <sub>C</sub> < 175°C		$V_{GSop}$	-5/+20	٧
Continuous Drain Current	Steady State	T <sub>C</sub> = 25°C	Ι <sub>D</sub>	17	Α
Power Dissipation			$P_{D}$	119	W
Continuous Drain Current	Steady State	T <sub>C</sub> = 100°C	I <sub>D</sub>	12	Α
Power Dissipation			$P_{D}$	59	W
Pulsed Drain Current (Note 2)	T <sub>A</sub> = 25°C		I <sub>DM</sub>	69	Α
Single Pulse Surge Drain Current Capability	T <sub>A</sub> = 25°0 R <sub>G</sub>	$C, t_p = 10 \mu s,$ = 4.7 Ω	I <sub>DSC</sub>	140	Α
Operating Junction and Storage Temperature Range			T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	°C
Source Current (Body Diode)			Is	11	Α
Single Pulse Drain-to-Source Avalanche Energy (I <sub>L(pk)</sub> = 23 A, L = 1 mH) (Note 3)			E <sub>AS</sub>	128	mJ

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

#### THERMAL CHARATERISTICS

Parameter	Symbol	Value	Unit
Junction-to-Case (Note 1)	$R_{\theta JC}$	1.3	°C/W
Junction-to-Ambient (Note 1)	$R_{\theta JA}$	40	°C/W

- The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
- 2. Repetitive rating, limited by max junction temperature.
- 3.  $E_{AS}$  of 128 mJ is based on starting  $T_J$  = 25°C; L = 1 mH,  $I_{AS}$  = 16 A,  $V_{DD}$  = 120 V,  $V_{GS}$  = 18 V.

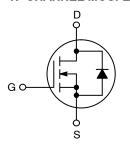


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V <sub>(BR)DSS</sub>	R <sub>DS(on)</sub> MAX	I <sub>D</sub> MAX
1200 V	224 mΩ @ 20 V	17 A

#### **N-CHANNEL MOSFET**





#### MARKING DIAGRAM



&Z = Assembly Plant Code &3 = Date Code (Year & Week)

&K = Lo

NVHL160N120SC1 = Specific Device Code

#### **ORDERING INFORMATION**

See detailed ordering and shipping information on page 2 of this data sheet.

#### **ELECTRICAL CHARACTERISTICS** (T<sub>J</sub> = 25°C unless otherwise stated)

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
OFF CHARACTERISTICS						
Drain-to-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 1 mA	1200	_	-	V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V <sub>(BR)DSS</sub> /T <sub>J</sub>	I <sub>D</sub> = 1 mA, referenced to 25°C	-	600	-	mV/°C
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 1200 V, T <sub>J</sub> = 25°C	_	_	100	μΑ
		V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 1200 V, T <sub>J</sub> = 175°C	-	_	250	
Gate-to-Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> = +25/-15 V, V <sub>DS</sub> = 0 V	-	_	±1	μΑ
ON CHARACTERISTICS						
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{GS} = V_{DS}$ , $I_D = 2.5 \text{ mA}$	1.8	3.1	4.3	V
Recommended Gate Voltage	$V_{GOP}$		-5	_	+20	V
Drain-to-Source On Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 20 V, I <sub>D</sub> = 12 A, T <sub>J</sub> = 25°C	-	162	224	mΩ
		V <sub>GS</sub> = 20 V, I <sub>D</sub> = 12 A, T <sub>J</sub> = 175°C	-	271	377	1
Forward Transconductance	9FS	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 12 A	-	3	-	S
CHARGES, CAPACITANCES & GATE	RESISTANCE			•		•
Input Capacitance	C <sub>ISS</sub>	V <sub>GS</sub> = 0 V, f = 1 MHz, V <sub>DS</sub> = 800 V	-	665	-	pF
Output Capacitance	C <sub>OSS</sub>	1 1	-	50	-	
Reverse Transfer Capacitance	C <sub>RSS</sub>	1	_	5	-	
Total Gate Charge	Q <sub>G(tot)</sub>	$V_{GS} = -5/20 \text{ V}, V_{DS} = 600 \text{ V}, I_D = 16 \text{ A}$	_	34	_	nC
Threshold Gate Charge	Q <sub>G(th)</sub>	1	_	6	_	
Gate-to-Source Charge	$Q_{GS}$	1	_	12.5	_	1
Gate-to-Drain Charge	Q <sub>GD</sub>	1	_	9.6	_	1
Gate Resistance	R <sub>G</sub>	f = 1 MHz	_	1.4	_	Ω
SWITCHING CHARACTERISTICS	l			<u>I</u>		
Turn-On Delay Time	t <sub>d(on)</sub>	$V_{GS} = -5/20 \text{ V}, V_{DS} = 800 \text{ V},$	_	11	_	ns
Rise Time	t <sub>r</sub>	I <sub>D</sub> = 16 A, R <sub>G</sub> = 6 Ω, Inductive Load	_	19	_	1
Turn-Off Delay Time	t <sub>d(off)</sub>		_	15	_	1
Fall Time	t <sub>f</sub>	1	_	8	_	1
Turn-On Switching Loss	E <sub>ON</sub>	1	_	200	_	μJ
Turn-Off Switching Loss	E <sub>OFF</sub>	1	_	34	_	1
Total Switching Loss	E <sub>TOT</sub>	1	_	234	-	1
DRAIN-SOURCE DIODE CHARACTER						
Continuous Drain-to-Source Diode Forward Current	I <sub>SD</sub>	$V_{GS} = -5 \text{ V}, T_{J} = 25^{\circ}\text{C}$	-	_	11	Α
Pulsed Drain-to-Source Diode Forward Current (Note 2)	I <sub>SDM</sub>	V <sub>GS</sub> = -5 V, T <sub>J</sub> = 25°C	-	_	69	Α
Forward Diode Voltage	$V_{SD}$	V <sub>GS</sub> = -5 V, I <sub>SD</sub> = 6 A, T <sub>J</sub> = 25°C	_	4	10	V
Reverse Recovery Time	t <sub>RR</sub>	$V_{GS} = -5/20 \text{ V}, I_{SD} = 16 \text{ A},$	_	15	-	ns
Reverse Recovery Charge	Q <sub>RR</sub>	dl <sub>S</sub> /dt = 1000 A/μs	_	45	-	nC
Reverse Recovery Energy	E <sub>REC</sub>	1 1	_	3.9	-	μJ
Peak Reverse Recovery Current	I <sub>RRM</sub>	1 1	_	6.2	-	A
<u> </u>		4		<b>!</b>		
Charge Time	Ta		_	7.4	_	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

#### **TYPICAL CHARACTERISTICS**

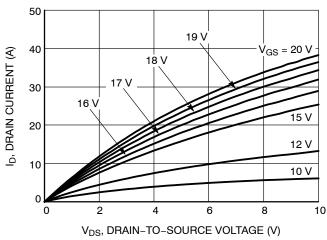


Figure 1. On-Region Characteristics

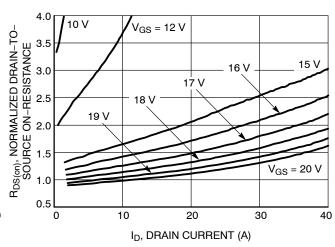


Figure 2. Normalized On-Resistance vs. Drain Current and Gate Voltage

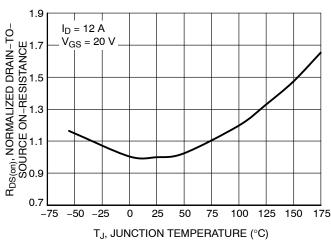


Figure 3. On–Resistance Variation with Temperature

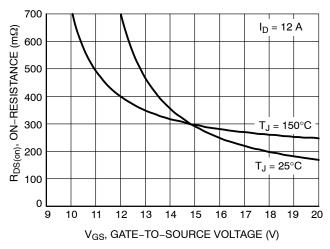


Figure 4. On-Resistance vs. Gate-to-Source Voltage

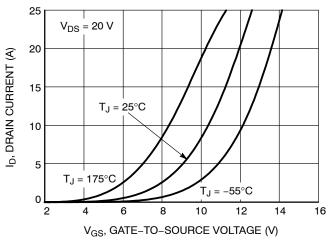


Figure 5. Transfer Characteristics

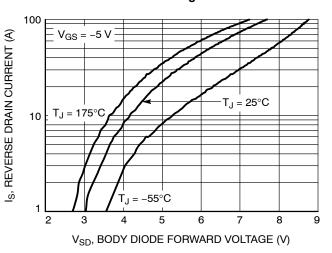


Figure 6. Diode Forward Voltage vs. Current

#### **TYPICAL CHARACTERISTICS**

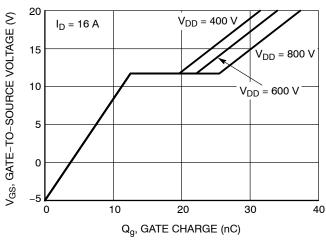


Figure 7. Gate-to-Source Voltage vs. Total Charge

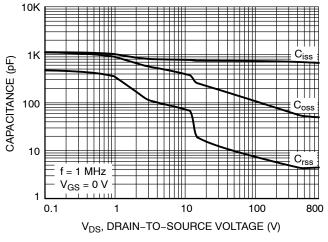


Figure 8. Capacitance vs. Drain-to-Source Voltage

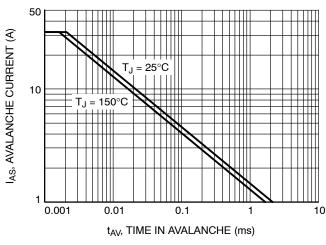


Figure 9. Unclamped Inductive Switching Capability

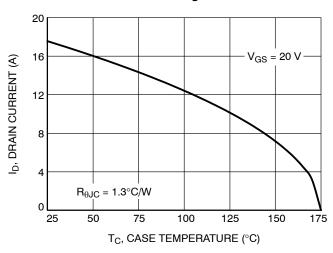


Figure 10. Maximum Continuous Drain Current vs. Case Temperature

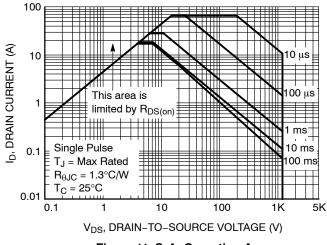


Figure 11. Safe Operating Area

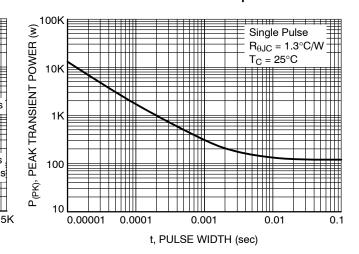


Figure 12. Single Pulse Maximum Power Dissipation

#### **TYPICAL CHARACTERISTICS**

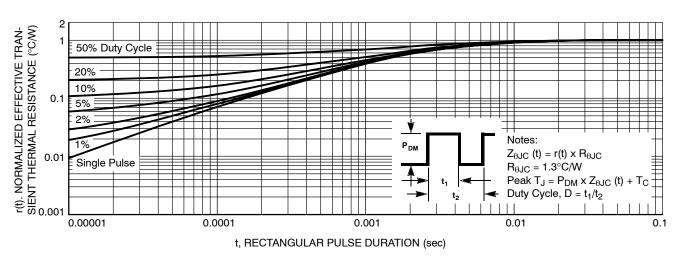
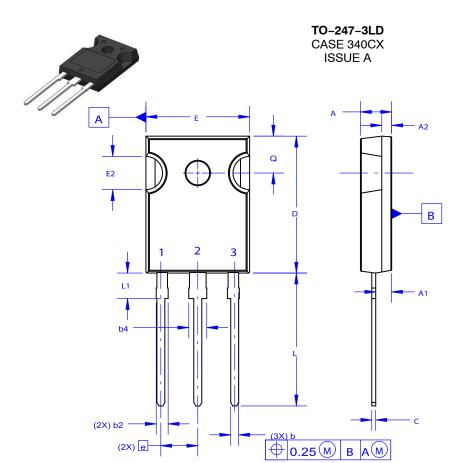


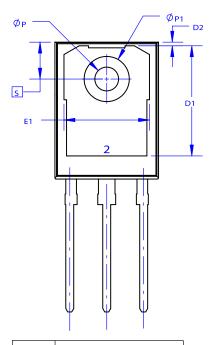
Figure 13. Junction-to-Ambient Thermal Response

#### PACKAGE MARKING AND ORDERING INFORMATION

Part Number	Top Marking	Package	Packing Method	Reel Size	Tape Width	Quantity
NVHL160N120SC1	NVHL160N120SC1	TO-247 Long Lead	Tube	N/A	N/A	30 Units



**DATE 06 JUL 2020** 

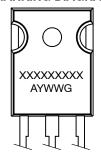


#### NOTES: UNLESS OTHERWISE SPECIFIED.

- A. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

  B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DRAWING CONFORMS TO ASME Y14.5 2009.
- D. DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED BY L1.
- E. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY L1.

#### **GENERIC MARKING DIAGRAM\***



XXXXX = Specific Device Code = Assembly Location

= Year WW = Work Week G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " =", may or may not be present. Some products may not follow the Generic Marking.

DIM	MILLIMETERS				
DIM	MIN	NOM	MAX		
Α	4.58	4.70	4.82		
<b>A</b> 1	2.20	2.40	2.60		
A2	1.40	1.50	1.60		
D	20.32	20.57	20.82		
Е	15.37	15.62	15.87		
E2	4.96	5.08	5.20		
е	~	5.56	~		
L	19.75	20.00	20.25		
L1	3.69	3.81	3.93		
ØΡ	3.51	3.58	3.65		
Q	5.34	5.46	5.58		
S	5.34	5.46	5.58		
b	1.17	1.26	1.35		
b2	1.53	1.65	1.77		
b4	2.42	2.54	2.66		
С	0.51	0.61	0.71		
D1	13.08	~	~		
D2	0.51	0.93	1.35		
E1	12.81	~	~		
ØP1	6.60	6.80	7.00		

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